



N0W03S43

♦Outline(L*W*H): 3.0*2.0*1.3 mm

♦Good thermal dissipation & optical uniformity

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Features

● Forward current: \(\secondsymbol{0} \) omA

• Typical viewing angle 50% Iv: 120°

• RoHS and REACH-compliant

Qualified according to JEDEC moisturevity
 Level 3

• Lens color: yellowish

• Package: 3,000pcs per reel

Applications

• Indoor lighting applications

• Flat backlight for LCD. Switch and symbol

Indicator and backlighting for all consumer electronics

Others applications

1	2	3	4	5
Process Type	Category	LED Type	Lead Frame Size	Dice wavelength &luminous rank
1 : normal process	S: SMD LED	C: PLCC top view D: PLCC side view	3020: 3.0* 2.0mm	Wxxx: white

7	8	9
Cap Color	PCB Module Code	Flow Code
W: yellowish	C: article mode	10: no expression above meaning for company
	-	Cap Color PCB Module Code

■ Maximum Rating(Ta=25°C)

Characteristics	Symbol	Typical	Unit
DC Forward Current	I_{F}	30	mA
Pulse Forward Current*3	$I_{ m PF}$	100	mA
Reverse Voltage	V_R	5	V
Junction Temperature	TJ	110	°C
Operating Temperature Range	T_{OP}	-40-80	°C
Storage Temperature Range	T_{STG}	-40-100	°C
Soldering Temperature*4	T_{SD}	260	°C

Notes 1: There is no maximum or typical voltage parameter

- 2: For other ambient, limited setting of current will be depended on de-rating curves.
- 3: Duty 1/10, pulse width 0.1ms
- 4: The maximum of soldering time is 5 seconds in T_{SD}

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■ Typical Product Characteristics(Ta=25°C)

Characteristics	Symbol	Min.	Тур.	Max.	Unit	Test condition
Forward Voltage	V_{F}	2.4	3.1	3.4	V	I _F =5mA
Luminous Intensity	Iv	350	460	1	mcd	I _F =5mA
Color Coordinate	X	-	0.3074	-		Ι 5.00 Λ
	у	-	0.3145	-	-	I _F =5mA
Reverse Current	I_R	-	-	10	μΑ	V _R = 5V
Viewing Angle	$2\theta_{1/2}$	-	120	-	deg	I _F =5mA

Notes: 1. Measurement Errors:

Forward Voltage: ±0.1V, Luminous Intensity: ±10%Iv, Color Coordinate: ±0.006

2. Electrical-Optical Characteristics (Ta=25°C)

■ Range of Bins

1) Forward Voltage Bins $(I_F = 5mA)$

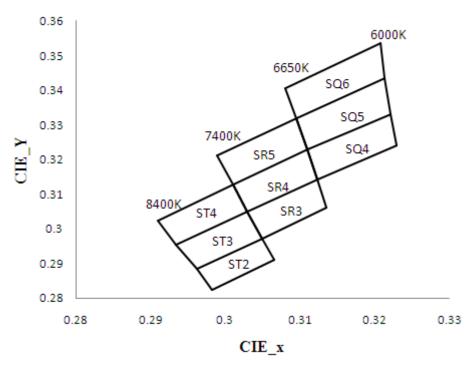
$V_{ m F}({ m V})$					
Bin Code	Min.	Max.			
A1	2.4	2.5			
A2	2.5	2.6			
B1	2.6	2.7			
B2	2.7	2.8			
C1	2.8	2.9			
C2	2.9	3.0			
D1	3.0	3.1			
D2	3.1	3.2			
E1	3.2	3.3			
E2	3.3	3.4			

2) Luminous Intensity Bins $(I_F = 5mA)$

I _V (mcd)					
Bin Code	Min.	Max.			
11	350	460			
12	460	600			
13	600	780			
14	780	1000			

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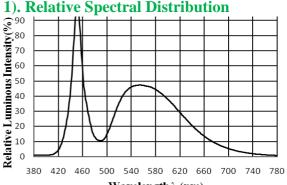


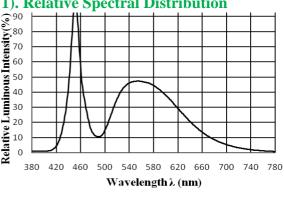
Color Rank

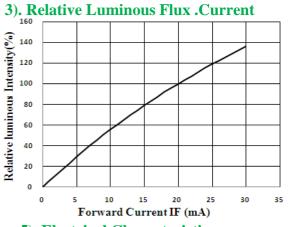
BIN	X	y	BIN	X	y	BIN	X	y
	0.308	0.3405		0.3095	0.332		0.311	0.323
506	0.3095	0.332	205	0.311	0.323	504	0.3124	0.3142
SQ6	0.3214	0.3434	SQ5	0.3222	0.3331	SQ4	0.3229	0.324
	0.3208	0.3535		0.3214 0.3434	0.3222	0.3331		
	0.2989	0.3213	CD 4	0.3011	0.3127	CD2	0.303	0.305
SR5	0.3011	0.3127		0.303	0.305		0.305	0.2972
SKS	0.311	0.323	SR4	0.3124	0.3142	SR3	0.3136	0.306
	0.3095	0.332		0.311	0.323		0.3124	0.3142
	0.291	0.3024		0.2934	0.2954		0.2962	0.2884
ST4	0.2934	0.2954	ST3	0.2962	0.2884	CT2	0.2983	0.2823
314	0.303	0.305	313	0.305	0.2972	ST2	0.3066	0.2912
	0.3011	0.3127		0.303	0.305		0.305	0.2972



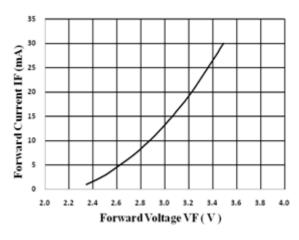
Optical Characteristics



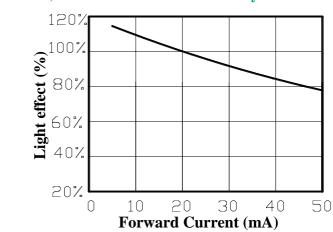




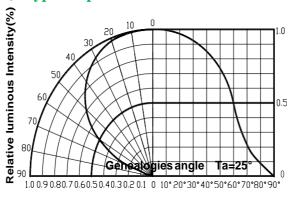




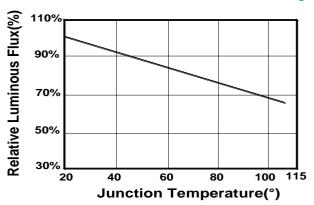
7). Relative Emission Efficiency. Current



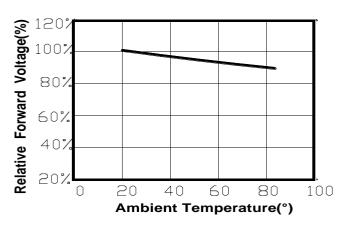
2). Typical Spatial Distribution



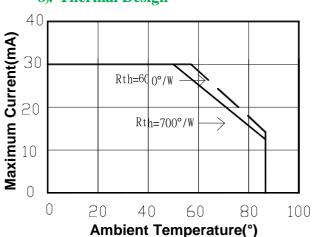
4). Relative Luminous Flux .Ambient Temperature



6). Relative Forward Voltage Temperature



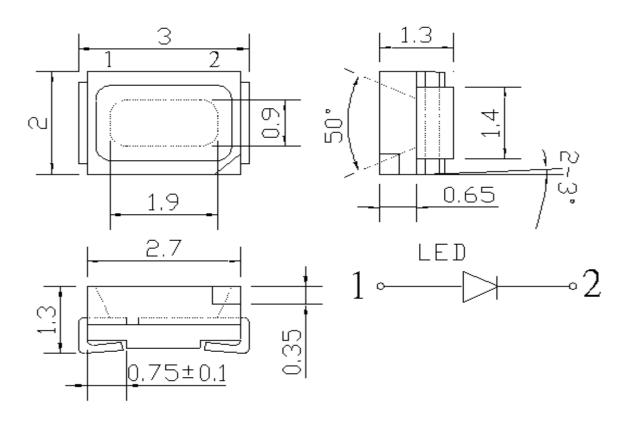
8). Thermal Design



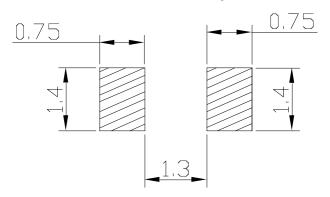
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Dimensions



Recommend Padlayout



Notes: 1. All dimensions are in millimeters

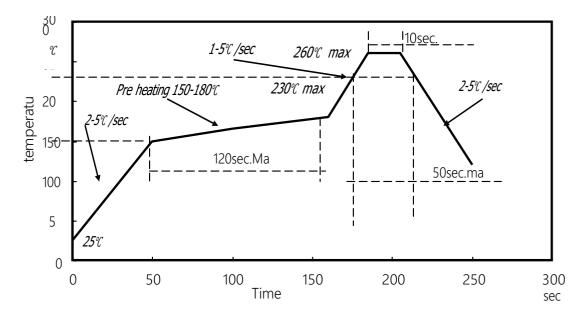
- 2. Tolerance is ± 0.1 mm unless otherwise noted
- 3. Specifications are subject to change without notice.

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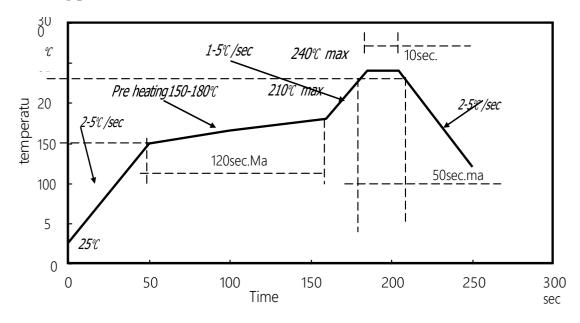


■ Reflow Profile

1. I_R reflow soldering profile for lead free solder



2. I_R reflow soldering profile for lead solder



Notes:

- 1. We recommend the reflow temperature $240^{\circ}\text{C}(\pm 5^{\circ}\text{C})$.the maximum soldering temperature should be limited to 260°C .
- 2. Don't cause stress to the silicone resin while it is exposed to high temperature.
- 3. Number of reflow process shall be less than 3 times.

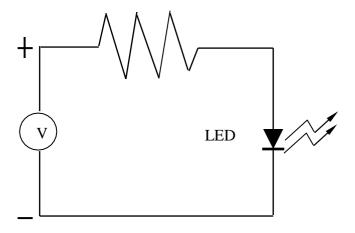
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■ Test Circuit and Handling Precautions

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1. Test Circuit



2. Handling Precautions

2.1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2.2. Storage

1). It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature: $5^{\circ}\text{C} \sim 30^{\circ}\text{C}(41^{\circ}\text{F} \sim 86^{\circ}\text{F})$

2). Shelf life in sealed bag: 12 month at $<5^{\circ}\text{C} \sim 30^{\circ}\text{C}$ and <60% R.H. after the package is Opened, the products should be used within a week or they should be keeping to stored at $\leq 20\%$ R.H. with ziplock sealed.

2.3. Baking

It is recommended to baking before soldering when the pack is unsealed after 24hrs.

The Conditions are as followings:

1). $.60\pm3$ °C X 6hrs and <5%RH, for reel

2). . 125±3°C X 2hrs, for single LED

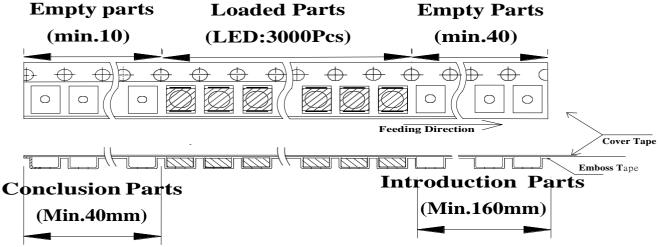
It shall be normal to see slight color fading of carrier (light yellow) after baking in process

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Packing

Feeding Direction (Unit: mm) **Dimensions of Reel (Unit: mm)** 73±0.10 Feeding Direction Labelposition 8.0 ±015 **Dimensions of Tape (Unit: mm)** 75±0.10 2.0±0.05 Ø1.55±0.05 0.20 4.0±0.10 25 ± 0.10 1.55 4.0±0.10 **Arrangement of Tape**



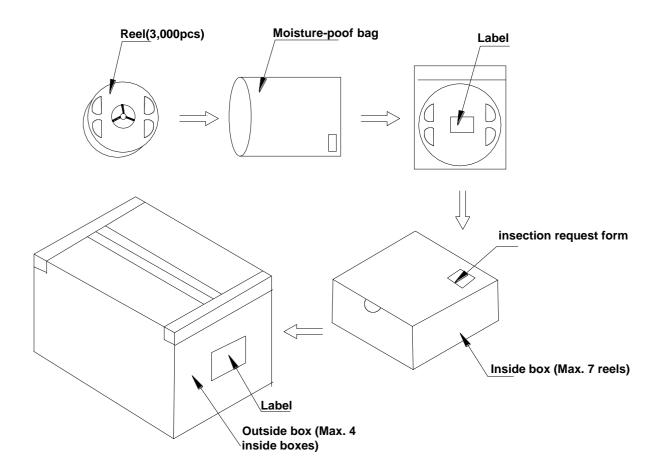
Notes:

- 1. Empty component pockets are sealed with top cover tape
- 2. The max loss number of SMD is 2pcs
- 3. The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications
- 4. 3,000pcs per reel



Packing

Packaging Specifications



Notes:

Reeled product (max.3,000) is packed in a sealed moisture-proof bag. Seven bags are packed in an inner box (size: about 260 X 230 X 100 mm) and four inner boxes are in an outer box (size: about 480 X 275 X 215 mm). On the label of moisture-poof bag, there should be the information of Part No., Lot No. and quantity number; also the total quantity number should be on inspection request form on outer box.

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Precautions

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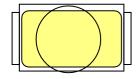
1. Abnormal situation caused by improper setting of collet

To choose the right collet is the key issue in improving the product's quality. LED is different from other electronic components, which is not only about electrical output but also for optical output. This characteristic made LED more fragile in the process of SMT. If the collet's lowering down height is not well set, it will bring damage to the gold wire at the time of collet's picking up and loading which will cause the LED fail to light up, light up now and then or other quality problems

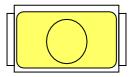
2. How to choose the collet

During SMT, please choose the collet that has larger outer diameter than the lighting area of lens, in case that improper position of collet will damage the gold wire inside the LED. Different collets fit for different products, please refer to the following pictures cross out

Outer diameter of collet should be larger than the lighting area







Picture 2(X)

3. Other points for attention

- A. No pressure should be exerted to the epoxy shell of the SMD under high temperature.
- B. Do not scratch or wipe the lens since the lens and gold wire inside are rather fragile and cross out easy to break.
- C. LED should be used as soon as possible when being taken out of the original package, and should be stored in anti-moisture and anti-ESD package.

4. This usage and handling instruction is only for your reference.

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OPTOELECTRONIC CO.,LTD Test Items and Results of Reliability

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Test Item	Test Conditions	Duration/ Cycle	Number of Damage	Reference
Temperature Cycle	-40 °C 30min ↑↓ 1 min 100 °C 30min	100 cycles	0/22	JEITA ED-4701 300 303
High Temperature Storage	T _a =100 °C±5 °C	1000 hrs	0/22	EIAJED-4701 200 201
High Humidity Heat Life Test	$T_a=85 \mathcal{C} \text{ RH}=85\%$ $I_F=20\text{mA}$	500 hrs	0/22	Tested with Brightek standard
Humidity Heat Storage	T _a =85 ℃ RH=85%	1000 hrs	0/22	EIAJED-4701 100 103
Life Test	$T_a=25 \mathcal{C}$ $I_F=20 \text{mA}$	1000 hrs	0/22	Tested with Brightek standard
Low Temperature Life Test	$T_a=-40\mathcal{C}$ $I_F=20\text{mA}$	1000 hrs	0/22	Tested with Brightek standard
High Temperature Life Test	$T_a=85 \mathcal{C}$ $I_F=20 \text{mA}$	1000 hrs	0/22	Tested with Brightek standard

*Criteria for Judging							
Item Symbol Condition Criteria for Judgment of I							
Item	Symbol	Condition	Min	Max			
Forward Voltage	V_{F}	I _F =5mA	-	$USL^{*1} \times 1.1$			
Reverse Current	I_R	V _R = 5V	-	10μΑ			
Luminous Intensity	Iv	I _F =5mA	LSL*2×0.7	-			

[Note] USL*1: Upper Specification Level

LSL*2: Lower Specification Level

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